Product Change Notification

Change Notification #: **116991 - 00**

Change Title: **Intel® Core™ and Intel® Xeon® Processors , PCN 116991-00, Manufacturing Site, Notification to Customers that China site will be enabled to perform both partial and full flow manufacturing**

Date of Publication: **June 19, 2019**

Key Characteristics of the Change:

Manufacturing Site

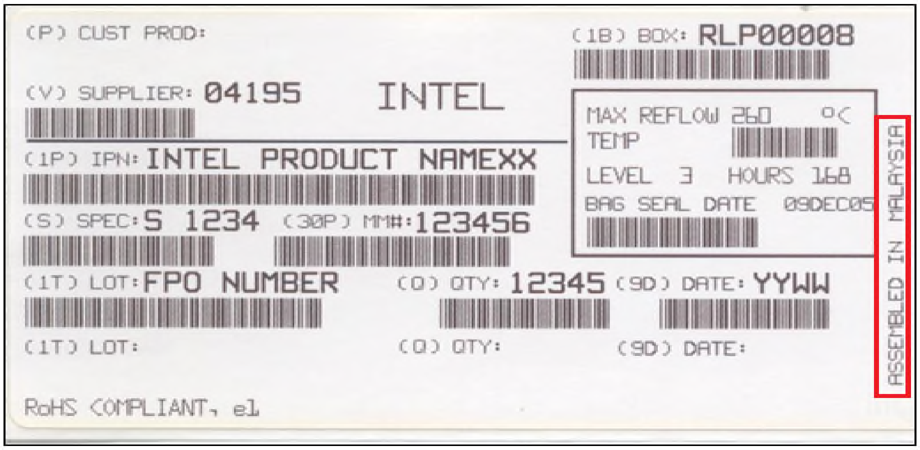
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 26, 2019

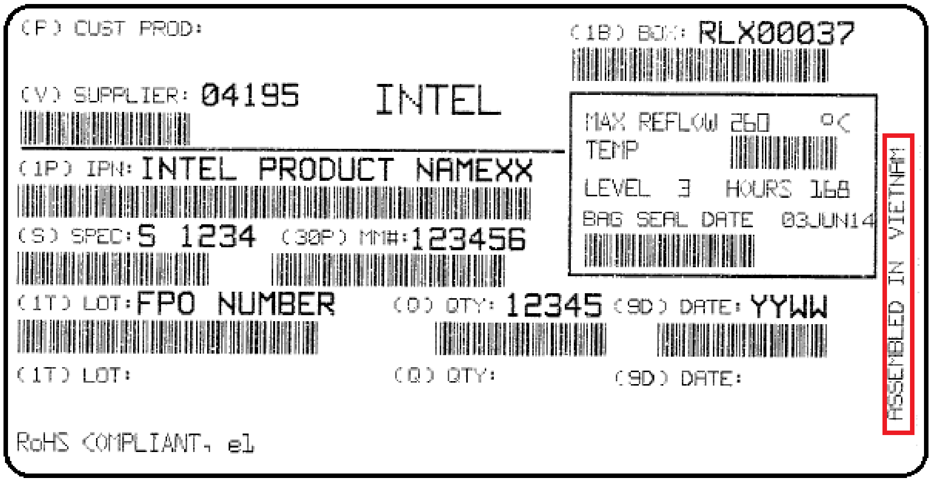
Description of Change to the Customer:

Intel has certified the China Manufacturing Site (CDAT) to perform full flow manufacturing (Assembly, Test, and Finish) as well as partial manufacturing among the three qualified sites for Assembly, Test, and Finish. Assembly, Test and Finish will continue to be done in PGAT (Malaysia) and VNAT (Vietnam) as well.
The Malaysia, Vietnam and China Manufacturing Sites have been certified equivalent (form, fit, function, and reliability) for the affected products and technologies of this change

With the possibility of full flow, or partial flow of material now coming from China, the value for the Country of Origin, on box labels, will now show either site (depending on the site which performed Assembly).



(P) CUST PROD:
(1B) BOX: RLP00008
(V) SUPPLIER: 04195 INTEL
MAX REFLOW 260 °C
TEMP
(1P) IPN: INTEL PRODUCT NAMEXX
LEVEL 3 HOURS 168
BAG SEAL DATE 09DEC05
(S) SPEC: S 1234 (30P) MM#: 123456
(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW
(1T) LOT: (Q) QTY: (9D) DATE:
RoHS COMPLIANT, e1
ASSEMBLED IN MALAYSIA



(P) CUST PROD:

(1B) BOX: RLX00037

(V) SUPPLIER: 04195 INTEL

MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 03JUN14

(1P) IPN: INTEL PRODUCT NAMEXX

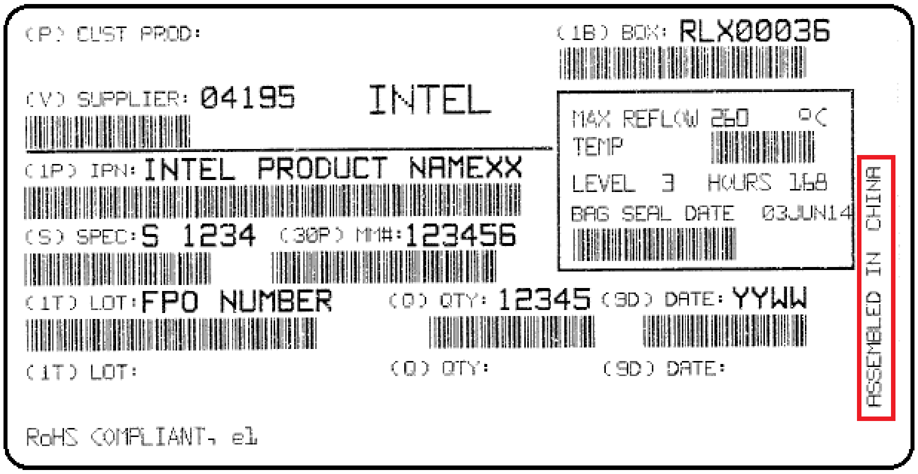
(S) SPEC: S 1234 (30P) MM#: 123456

(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW

(1T) LOT: (Q) QTY: (9D) DATE:

RoHS COMPLIANT, e1

ASSEMBLED IN VIETNAM



(P) CUST PROD:

(1B) BOX: RLX00036

(V) SUPPLIER: 04195 INTEL

MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 03JUN14

(1P) IPN: INTEL PRODUCT NAMEXX

(S) SPEC: S 1234 (30P) MM#: 123456

(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW

(1T) LOT: (Q) QTY: (9D) DATE:

RoHS COMPLIANT, e1

ASSEMBLED IN CHINA

China’s manufacturing activity today:

Prior Scenarios	**Present/To-Be Scenarios**
Full flow Assembly, Test and Finish Process certified in Malaysia Mfg site (PGAT) and Vietnam Site (VNAT)	Assembly, Test and Finish Process certified in Malaysia Mfg site (PGAT) and Vietnam Site (VNAT) and China site (CDAT)
Partial Assembly (PGAT) with Test and Finish Process certified in VNAT	Partial Assembly (PGAT) with Test and Finish Process certified in VNAT or CDAT
	Partial Assembly (VNAT) with Test and Finish Process certified in PGAT or CDAT
	Partial Assembly (CDAT) with Test and Finish Process certified in VNAT or PGAT

Customer Impact of Change and Recommended Action:

Customers should notify their receiving department of the additional country involved in the manufacturing of the products impacted. It is possible that Customers may receive finished materials manufactured entirely at one of the three qualified sites or split between the three sites to accomplish Assembly, Test and Finish.

Customers may contact their Intel Field Sales Representative or the contacts listed on the last page of this Product Change Notification appropriate to your geo with questions.

Products Affected / Intel Ordering Codes:

Marketing Name	Platform	Product Code	S-Spec	MM#
Intel® Xeon® E-2278G Processor	WORKSTATION	CM8068404225303	S RFB2	999CD4
Intel® Xeon® E-2288G Processor	WORKSTATION	CM8068404224102	S RFB3	999CD6
Intel® Core™ i5-9400 Processor	DESKTOP	CM8068403875505	S RG0Y	999H28
Intel® Core™ i5-9400F Processor	DESKTOP	CM8068403875510	S RG0Z	999H29
Intel® Core™ i5-9500F Processor	DESKTOP	CM8068403875414	S RG10	999H2A
Intel® Core™ i5-9600K Processor	DESKTOP	CM8068403874405	S RG11	999H2C
Intel® Core™ i5-9600KF Processor	DESKTOP	CM8068403874410	S RG12	999H2D
Intel® Core™ i7-9700 Processor	DESKTOP	CM8068403874521	S RG13	999H2F
Intel® Core™ i7-9700F Processor	DESKTOP	CM8068403874523	S RG14	999H2G
Intel® Core™ i7-9700K Processor	DESKTOP	CM8068403874215	S RG15	999H2H
Intel® Core™ i7-9700KF Processor	DESKTOP	CM8068403874220	S RG16	999H2J
Intel® Core™ i7-9700T Processor	DESKTOP	CM8068403874912	S RG17	999H2L
Intel® Core™ i9-9900 Processor	DESKTOP	CM8068403874032	S RG18	999H39
Intel® Core™ i9-9900K Processor	DESKTOP	CM8068403873925	S RG19	999H3A
Intel® Core™ i9-9900KF Processor	DESKTOP	CM8068403873928	S RG1A	999H3C
Intel® Core™ i9-9900T Processor	DESKTOP	CM8068403874122	S RG1B	999H3D

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 19, 2019	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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